

# MECHANICAL CASE OUTLINE

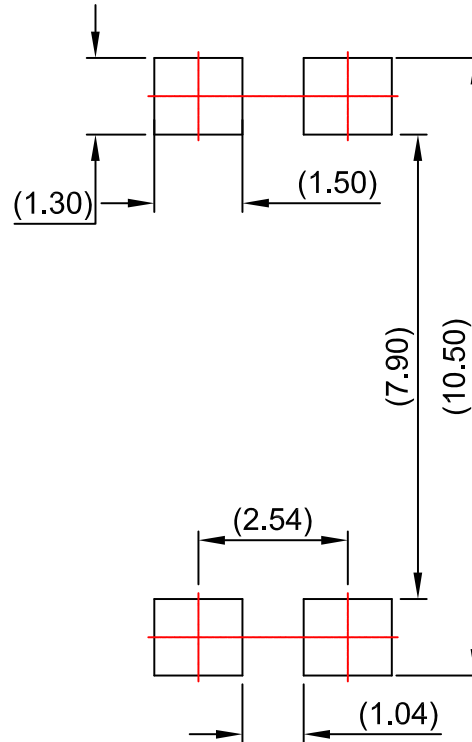
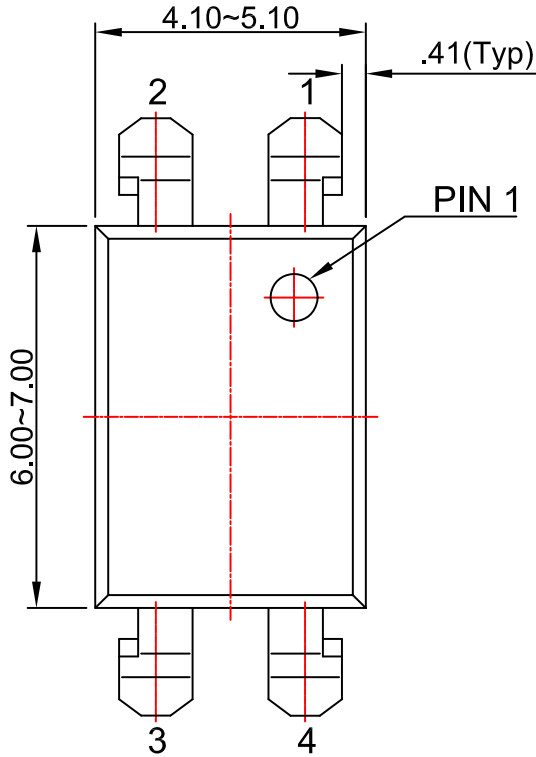
## PACKAGE DIMENSIONS

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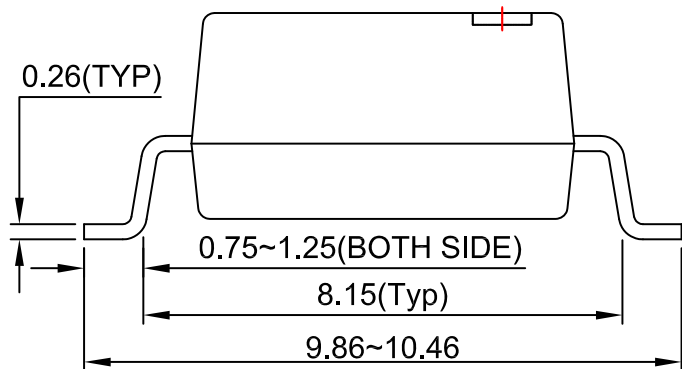
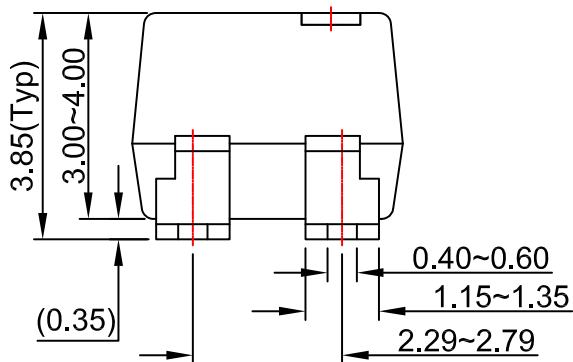


PDIP4 GW  
CASE 709AH  
ISSUE A

DATE 31 JUL 2016



LAND PATTERN RECOMMENDATION



**NOTES:**

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- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSION

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